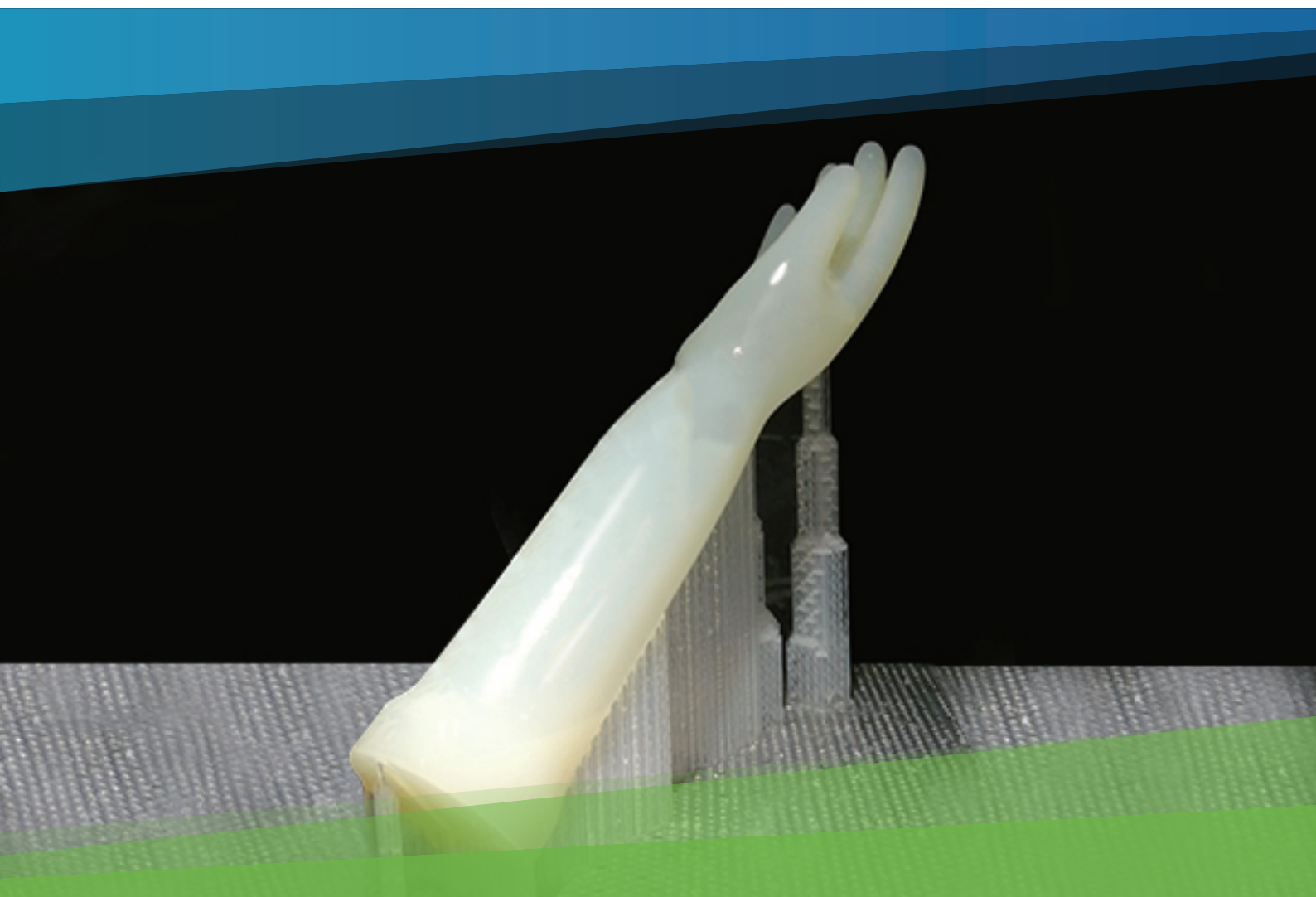


TECHNICAL DATA

KS1208H

Product Demonstration



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Material Overview

KS1208H is a high temp resistant SLA resin with low-viscosity in semitranslucent color. The part can be used with a temperature around 120°C. For instantaneous temperature it is resistant to above 200°C. It has good dimensional stability and fine surface details, which is perfect solution for parts requiring resistance to heat and humidity, and it's also applicable for quick mold with certain material in small batch production.

Advantages

- High temperature resistance
- Excellent dimensional stability
- High strength and accuracy

Ideal Applications

- Prototypes need high-temp resistance
- Quick mold

Technical Datasheet

Liquid Properties		Optical Properties		
Appearance	Semi-translucent	Dp	0.115 mm	[slope of cure-depth vs. ln (E) curve]
Viscosity	340 cps @ 28 °C	Ec	13.5 mJ/cm ²	[critical exposure]
Density	1.14g/cm ³ @ 25 °C	Building layer thickness	0.08–0.12mm	0.08–0.12mm

Mechanical Properties		UV Postcure		
TEST ITEMS	TEST METHOD	NUMERICAL VALUE	TEST METHODS	NUMERICAL VALUE
Tensile Strength	ASTM D 638	65MPa	GB/T1040.1–2006	71MPa
Elongation at break	ASTM D 638	3–5%	GB/T1040.1–2006	3–5%
Bending strength	ASTM D 790	110MPa	GB/ T9341–2008	115MPa
Flexural modulus	ASTM D 790	2720MPa	GB/ T9341–2008	2850MPa
Izod notched impact strength	ASTM D 256	20J/m	GB/T1843–2008	25J/m
Shore hardness	ASTM D 2240	87D	GB/T2411–2008	87D
Glass transition temperature	DMA, tan θ peak	135°C	58 – 70	58 – 70
Thermal expansion coefficient (25–50°C)	ASTME831–05	50 μ m/m°C	GB/T1036–89	50 μ m/m°C
Thermal expansion coefficient (50–100°C)	ASTME831–05	150 μ m/m°C	GB/T1036–89	160 μ m/m°C

Recommended temperature for processing and storage of the above resin should be 18°C–25°C.

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